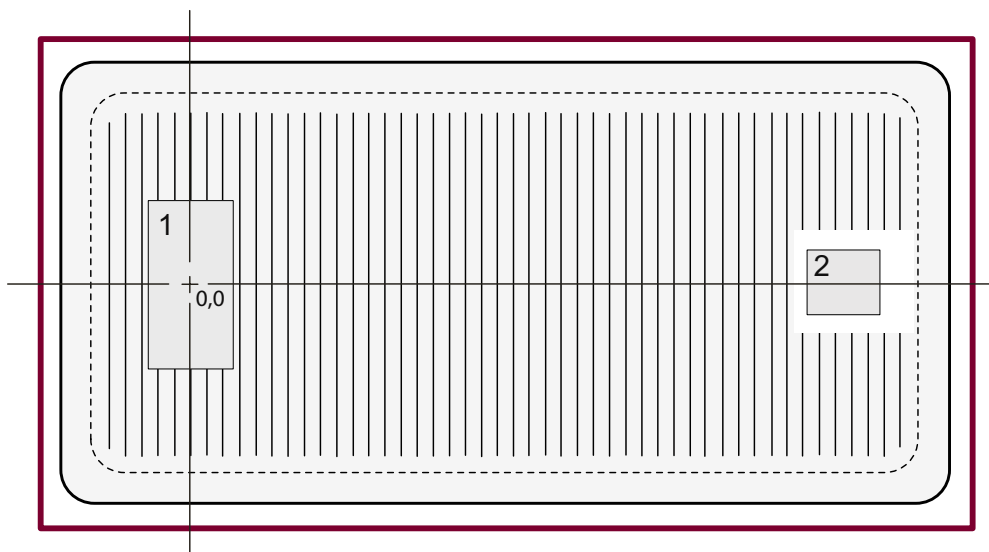


**Pad Layout**



**Backside: Drain**

**Die Specifications**

Device	Die Dimensions			Back Side Metal	Back Side	Bonding Pad Material
	Length <sup>1</sup> (mils)	Width <sup>1</sup> (mils)	Thickness (mils)			
TN5335	30	56	8.0 ± 1.0	Au	Drain	Al/Cu/Si

**Bonding Pad Description**

Pad #	Function	x Position <sup>2</sup> (mils)	y Position <sup>2</sup> (mils)	x Size (mils)	y Size (mils)
1	Source	0	0	5.0	9.9
2	Gate	38.3	0	4.3	3.9

**Notes:**

1. Maximum values.
2. Position referenced to center of pad.

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